HDMI A S1H 2.0N1 RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

HDMI sockets for PCBs - reliable connectivity for your electronics projects

HDMI sockets from Weidmüller offer a high-quality solution for the transmission of video, audio and Ethernet signals (HEC) in industrial applications

Features and benefits:

- Compact design: Ideal for space-saving PCB designs thanks to various outlet directions
- High data transmission rate: Supports HDMI 2.0 and 4K resolutions and Ethernet up to 100 Mbit/s
- Easy integration: Standardized design facilitates mounting and integration into the device
- EMC protection: Reliable protection against interference for clean data transmission
- Perfectly suited for processing in automated SMT processes thanks to tape-on-reel packaging
- Durability: Robust design ensures a reliability in demanding environments

General ordering data

Version	, female header, Solder flange, SMD solder connection, 0.50 mm, Number of poles: 19, 90°, Gold over nickel, black, Reel
Order No.	3107650000
Type	HDMI A S1H 2.0N1 RL
GTIN (EAN)	4099987174541
Qty.	3,000 pc(s).
Packaging	Reel

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Technical data

Dimensions and weights

Depth	11.55 mm	Depth (inches)	0.455 inch
Height	6.18 mm	Height (inches)	0.243 inch
Width	15 mm	Width (inches)	0.591 inch
Net weight	0.003 g		

System specifications

LED	No	Mounting onto the PCB	SMD solder connection
Number of poles	19	Number of solder pins per pole	1
Outgoing elbow	90°	Pitch in inches (P)	0.02 "
Pitch in mm (P)	0.5 mm	Plugging cycles	≥ 10000
Protection degree	IP20	Shield surface	nickel-plated
Shield tabs	none	Shielding	Yes
Shielding material	Copper alloy	Side termination, characteristic	Solder flange
Soldering process	Reflow soldering, Manual soldering	Type of connection	Socket connector

Electrical properties

Dielectric strength, contact / contact	500 V AC / 1 min	Insulation strength	≥ 100 MΩ
Rated voltage	0.5 V		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Copper alloy
Contact surface	Gold over nickel	Storage temperature, min.	-20 °C
Storage temperature, max.	65 °C	Operating temperature, min.	-20 °C
Operating temperature, max.	65 °C		

Packing

Packaging	Reel	VPE length	0 mm
VPE width	0 mm	VPE height	0 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01	ECLASS 15.0	27-46-02-01

Approvals

ROHS	Conform

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

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Technical data

Downloads

Engineering Data	CAD data – STEP
Technical Documentation	3107650000_HDMI_A_S1H_2.0N1_RL_20241127 Customer Drawing Customer Drawing

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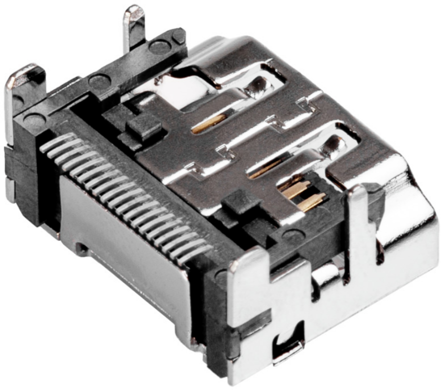
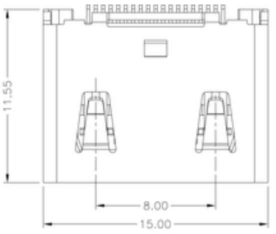
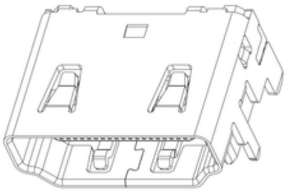
Drawings

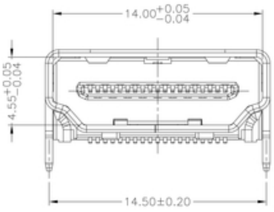


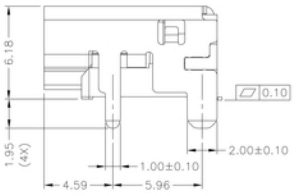
Drawings

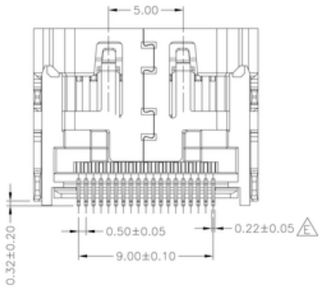


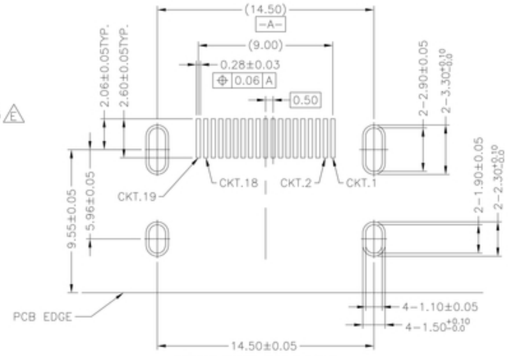


3D View









RECOMMENDED PCB LAYOUT

Reflow Solder Profile

Recommended reflow soldering profile

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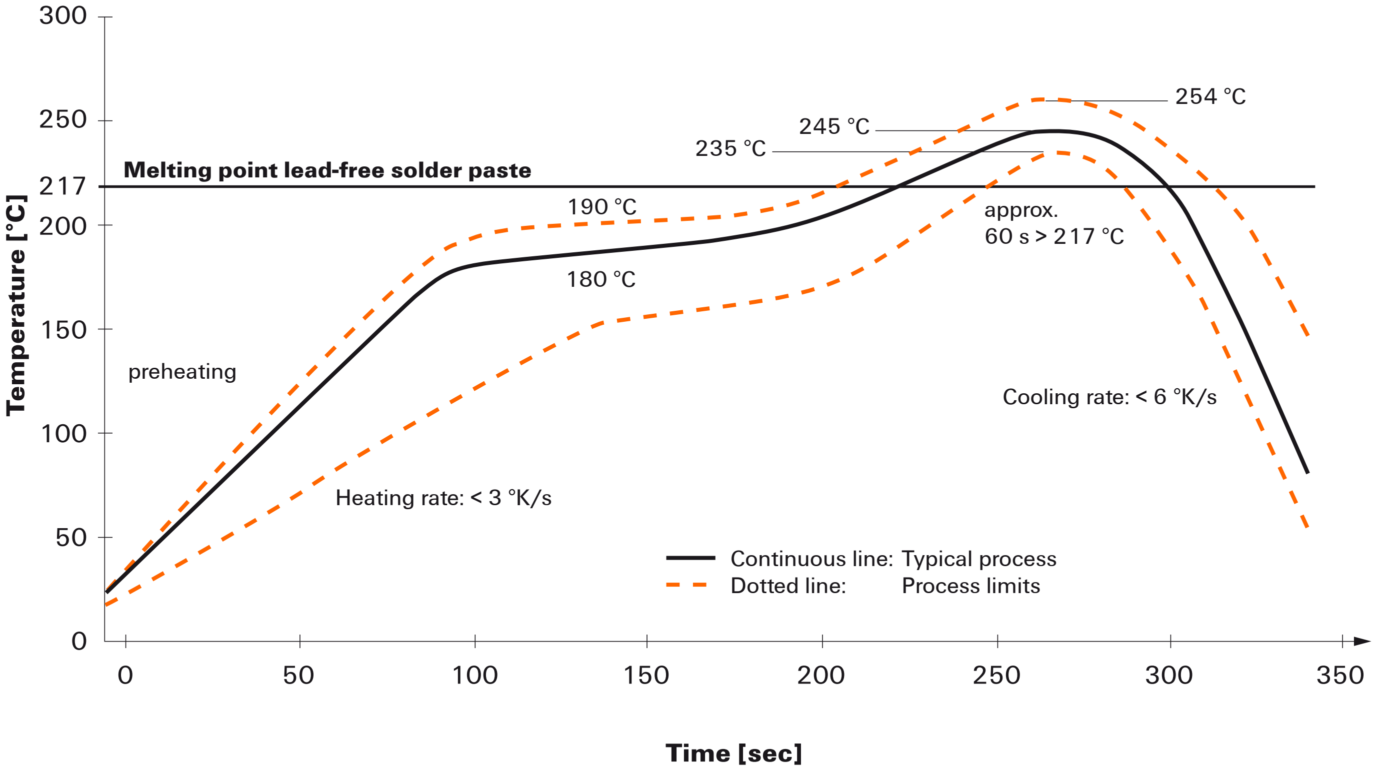

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.